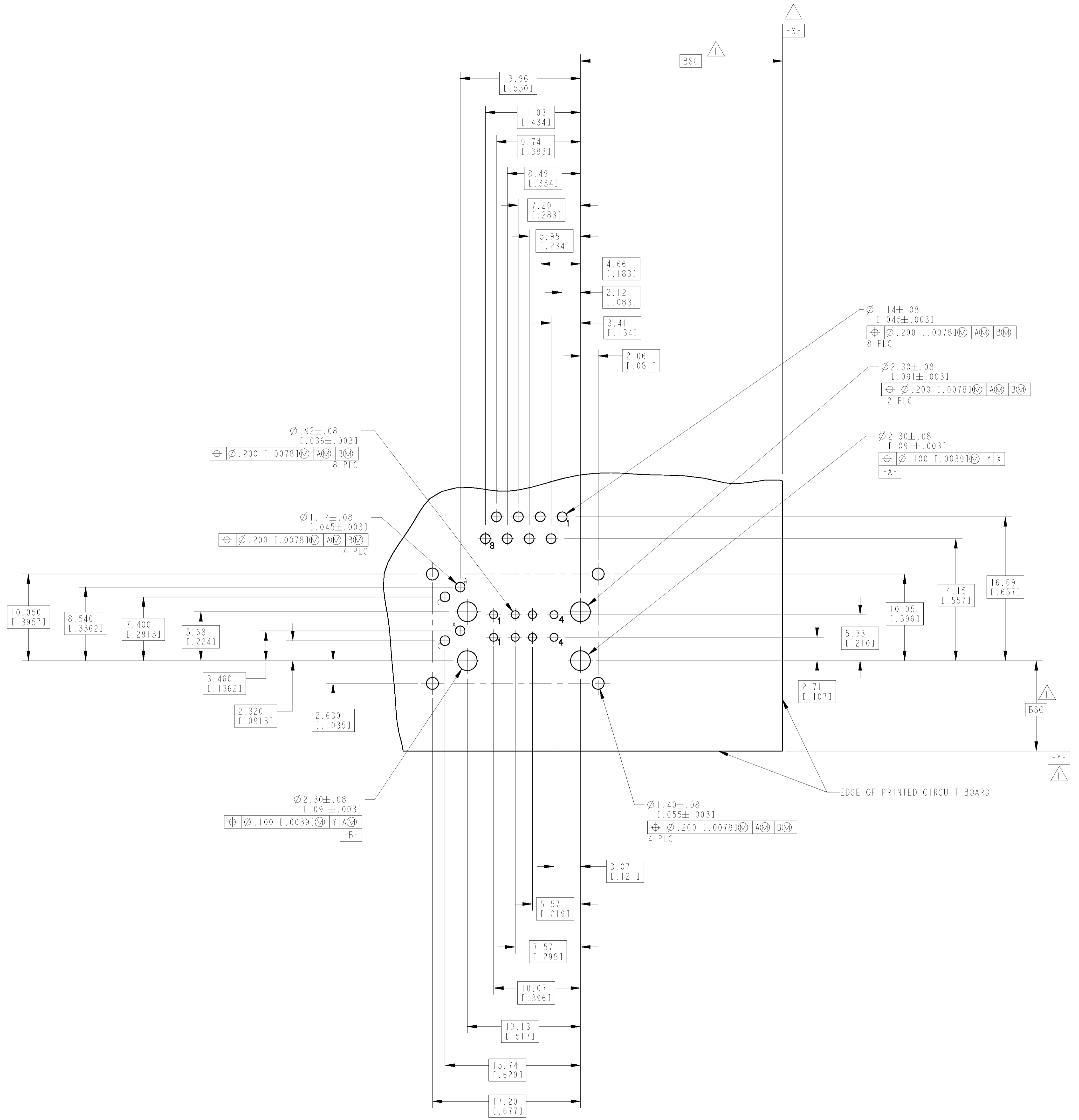


LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DRN	APVD		
-	-	SEE SHEET 1	-	-	-		



RECOMMENDED PCB LAYOUT \triangle

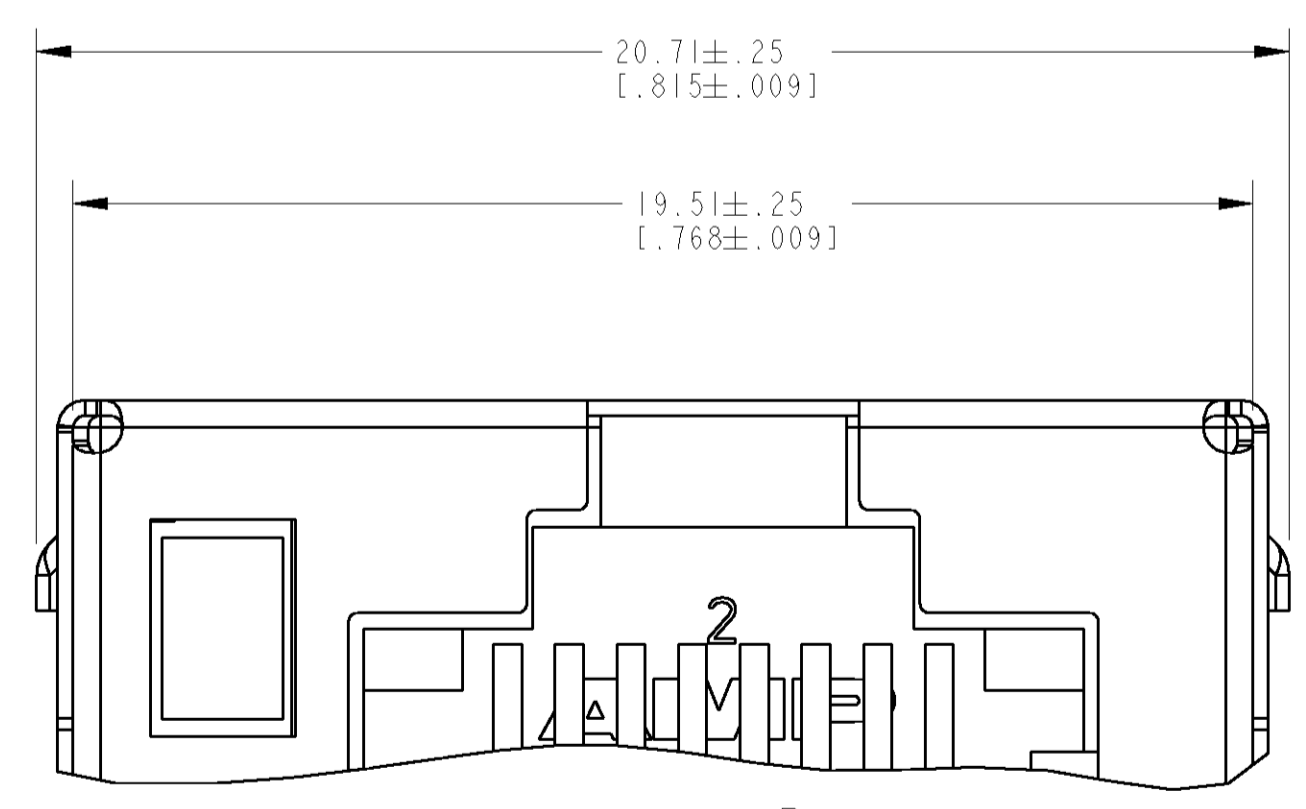
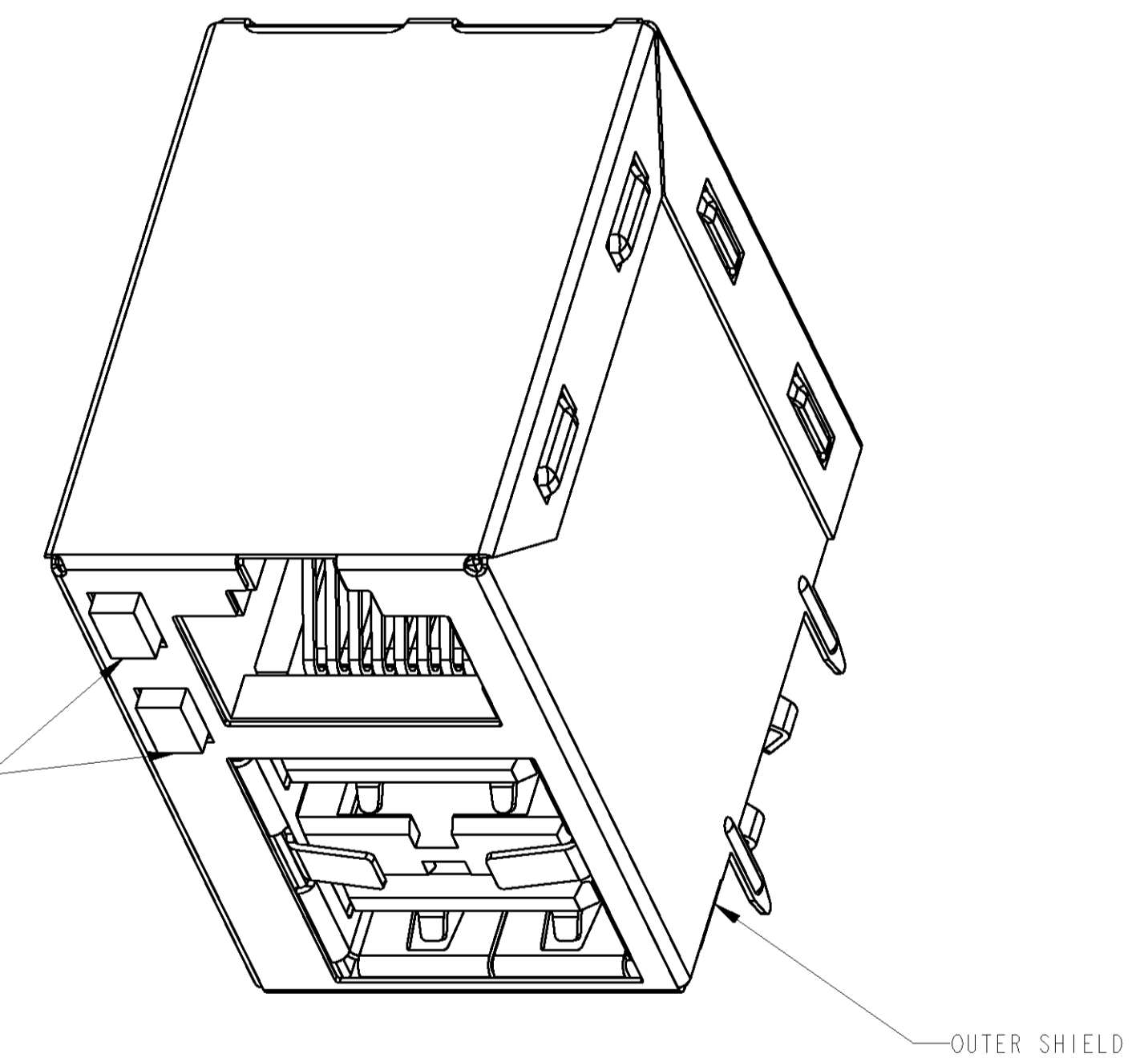
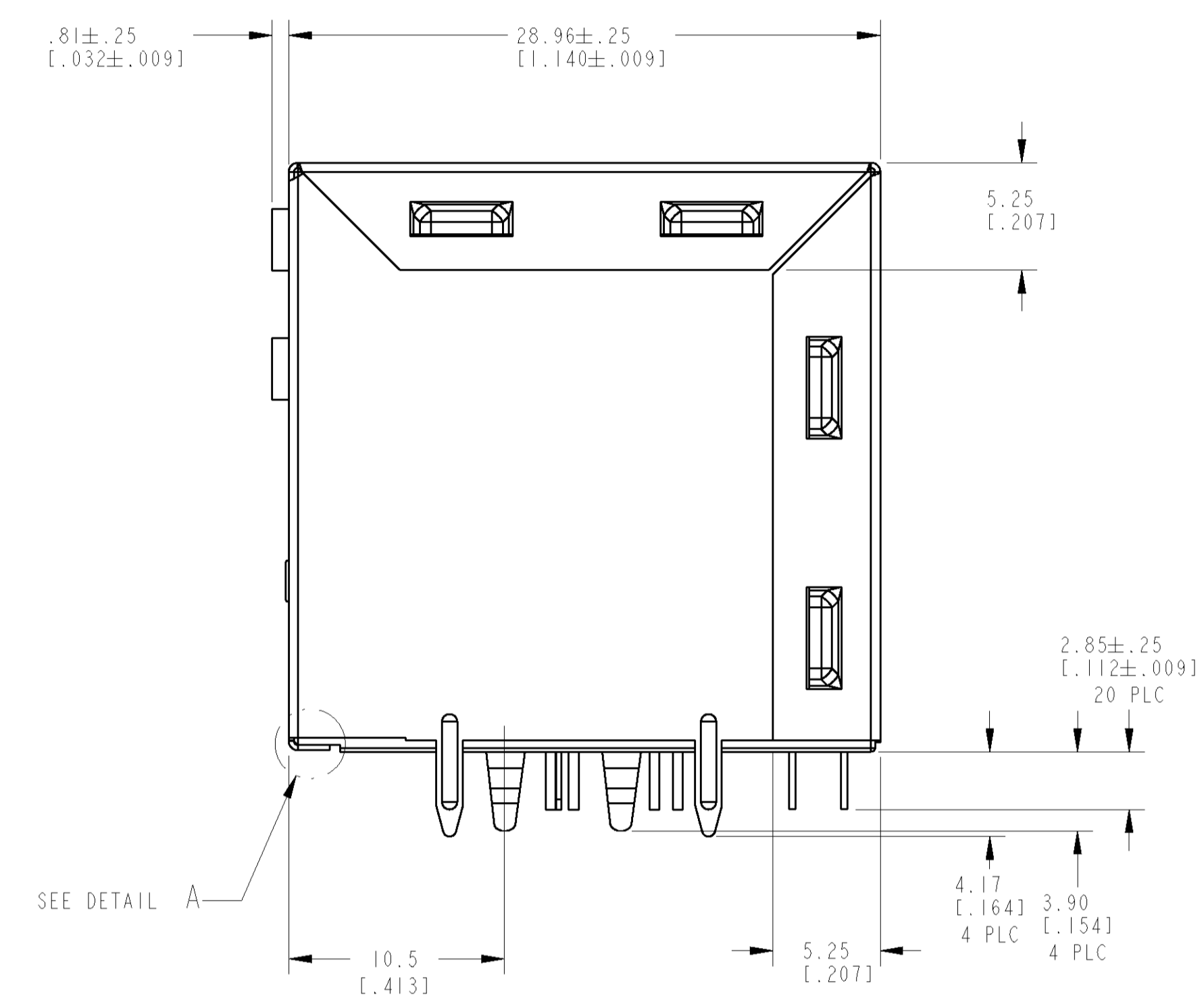
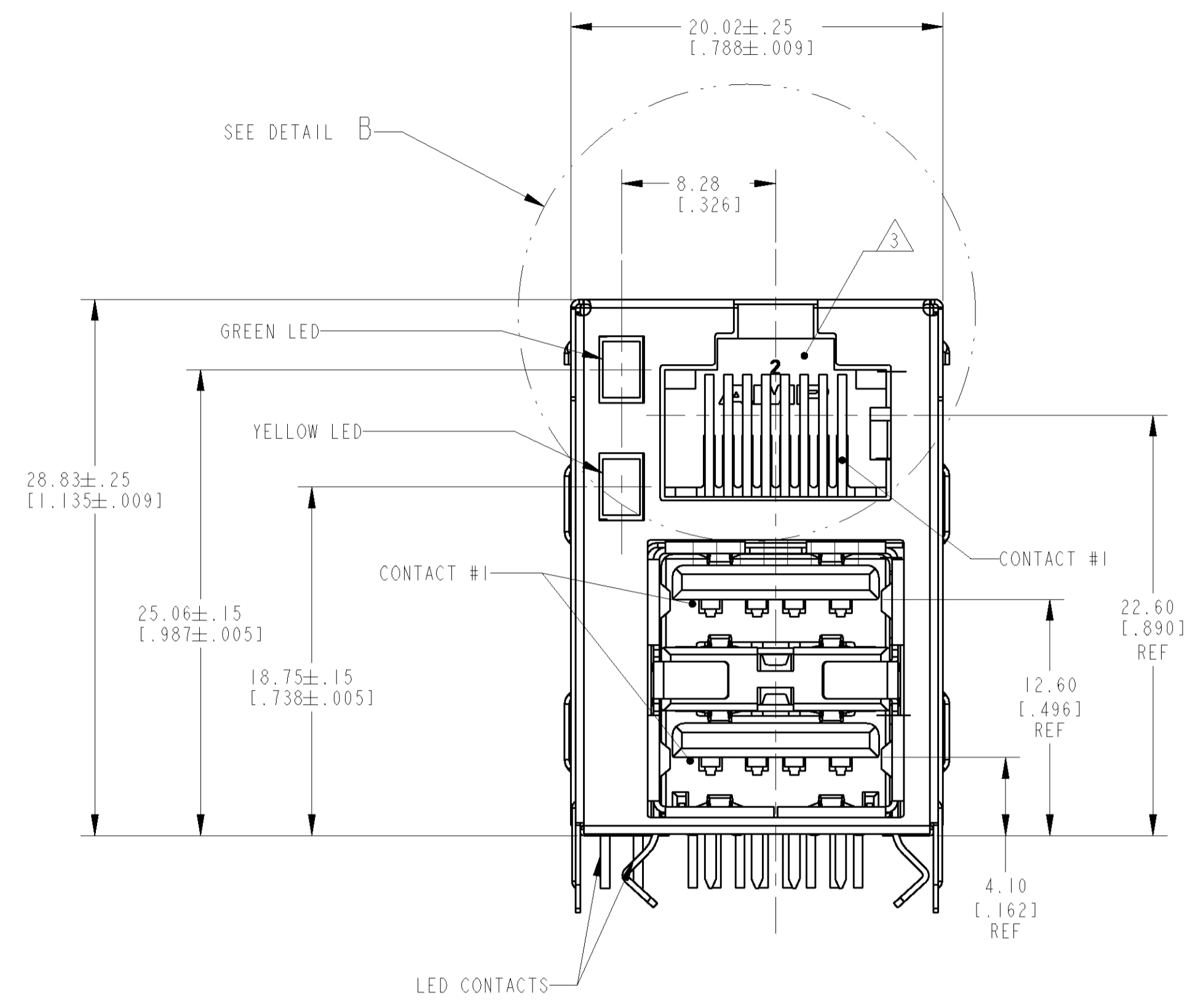
<small>THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION. ALL RIGHTS RESERVED. THIS DRAWING IS THE PROPERTY OF TYCO ELECTRONICS CORPORATION. IT IS TO BE USED ONLY FOR THE SPECIFIC PARTS AND ASSEMBLIES IDENTIFIED HEREIN. IT IS NOT TO BE REPRODUCED OR TRANSMITTED IN ANY FORM OR BY ANY MEANS, ELECTRONIC OR MECHANICAL, INCLUDING PHOTOCOPYING, RECORDING, OR BY ANY INFORMATION STORAGE AND RETRIEVAL SYSTEM, WITHOUT THE WRITTEN PERMISSION OF TYCO ELECTRONICS CORPORATION.</small>		DRN: J. GERACE/L. A. MAYER CDR: J. WESTMAN APVD: S. FLICKINGER DATE: 14APR2005	tyco Electronics AMP Incorporated Harrisburg, PA 17105-3608
DIMENSIONS: mm [INCHES] 	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.13(.005) 3 PLC ± 4 PLC ± ANGLES ±1°	NAME: ASSEMBLY, RJ-45 MODULAR JACK OVER STACKED USB RECEPTACLE PRODUCT SPEC: APPLICATION SPEC: WEIGHT:	SIZE: A CAGE CODE: 00779 DRAWING NO: C=6116640 RESTRICTED TO:
MATERIAL: SEE NOTE 4 FINISH: SEE NOTE 4	CUSTOMER DRAWING	SCALE: 4:1 SHEET: 2 OF 2 REV: A	

LOC	DIST	REVISIONS					
AA	22	P	LTR	DESCRIPTION	DATE	DRN	APVD
		A		ECOS11-0204-04	14APR2005	LAM	SF

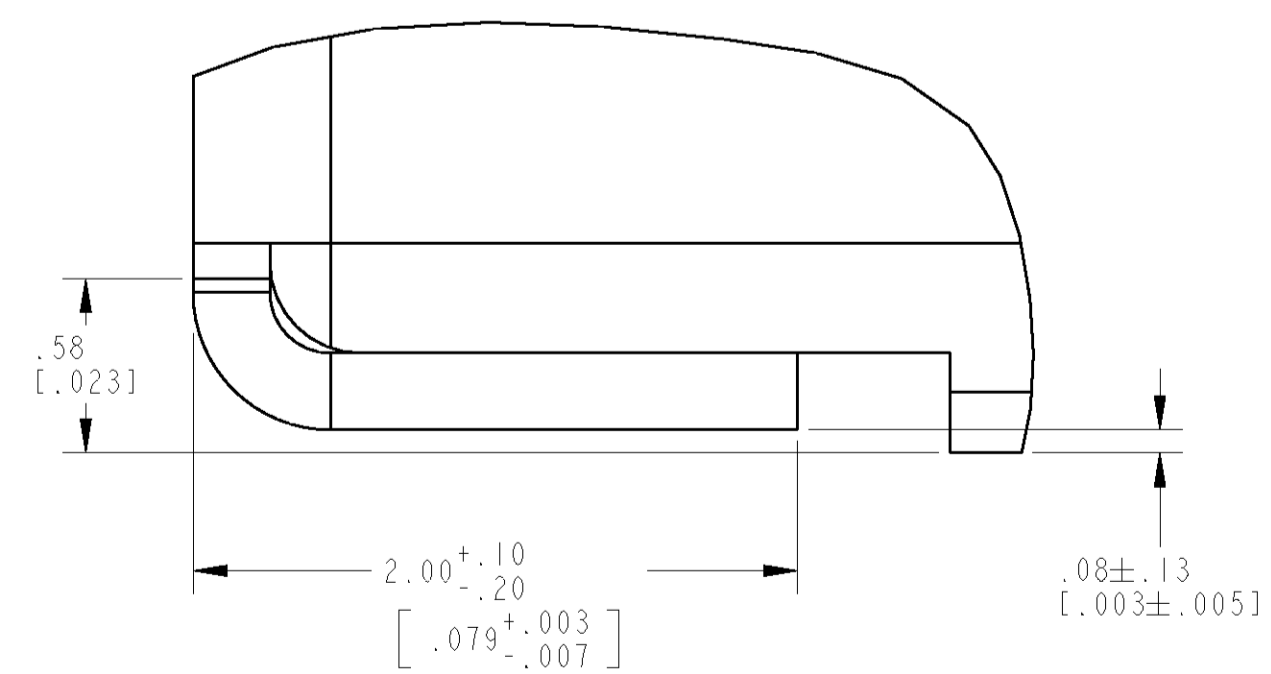
- 1 DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER.
- 2 RECOMMENDED PC BOARD THICKNESS IS 2.36(.093.)
- 3 RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F

4. MATERIAL:

HOUSING: PLASTIC HOUSINGS: UL94V-0/5V THERMOPLASTIC. SEE TABLE FOR COLOR.
 TERMINAL: USB: 0.251±0.013 THICK PHOSPHOR BRONZE PLATED WITH 1.27µm NICKEL. IN LOCALIZED GOLD PLATE AREA 0.076µm MIN GOLD OVER 0.76µm MIN PALLADIUM-NICKEL IS ADDED OVER NICKEL UNDERPLATE. IN SOLDER AREA 3.8µm MIN TIN IS ADDED OVER NICKEL UNDERPLATE.
 RJ45: 0.318 THICK PHOSPHOR BRONZE PLATED WITH 1.27µm MIN THICK NICKEL. IN LOCALIZED GOLD PLATE AREA 1.27µm MIN THICK GOLD IS ADDED OVER NICKEL UNDERPLATE. IN SOLDER AREA 3.8µm MIN TIN IS ADDED OVER NICKEL UNDERPLATE.
 LED: 0.5 DIAMETER CARBON STEEL LEADS PREPLATED WITH 8.89 µm THICK Sn/Cu, OVER 2.03 µm THICK Ag, OVER 1.02 µm THICK Cu, OVER 3.56 µm THICK Ni, OVER 1.02 µm Cu UNDERPLATE
 SHIELD: OUTER: 0.254 THICK COPPER-ZINC ALLOY PREPLATED WITH TIN 2µm TO 3.8µm THICK.
 INNER: 0.318 THICK COPPER-ZINC ALLOY PREPLATED WITH TIN 2µm TO 3.8µm THICK.
 USB: 0.318 THICK PHOSPHOR-BRONZE PREPLATED WITH 5.1µm MIN TIN



DETAIL B
SCALE 8:1



DETAIL A
SCALE 40:1

WITH LEDS	6116640-1
DESCRIPTION	PART NO.

<small>THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION BY TICO ELECTRONICS CORPORATION. ALL RIGHTS RESERVED.</small>		DWN: J. GERACE/L. 14APR2005 ENR: J. WESTMAN 14APR2005 APVD: S. FLICKINGER 14APR2005	AMP Incorporated Harrisburg, PA 17105-3608
DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.13(.005) 3 PLC ± 4 PLC ± ANGLES ±1°	NAME: S. FLICKINGER PRODUCT SPEC: APPLICATION SPEC: FINISH: SEE NOTE 4	ASSEMBLY, RJ-45 MODULAR JACK OVER STACKED USB RECEPTACLE SIZE: A 00779 C=6116640 SCALE: 4:1 SHEET 1 OF 2 REV A
MATERIAL: SEE NOTE 4	FINISH: SEE NOTE 4	WEIGHT: -	CUSTOMER DRAWING